

SOT1193-2

plastic, extremely thin quad flat package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN8
Package type industry code	XQFN8
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-255
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	17-1-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.55	-	1.6	1.65	mm
E	package width		1.55	-	1.6	1.65	mm
A	seated height		[tbd]	-	[tbd]	0.5	mm
e	nominal pitch		-	-	0.55	-	mm
n ₂	actual quantity of termination		-	-	8	-	



2. Package outline

XQFN8: plastic, extremely thin quad flat package; no leads;
8 terminals; body 1.6 x 1.6 x 0.5 mm

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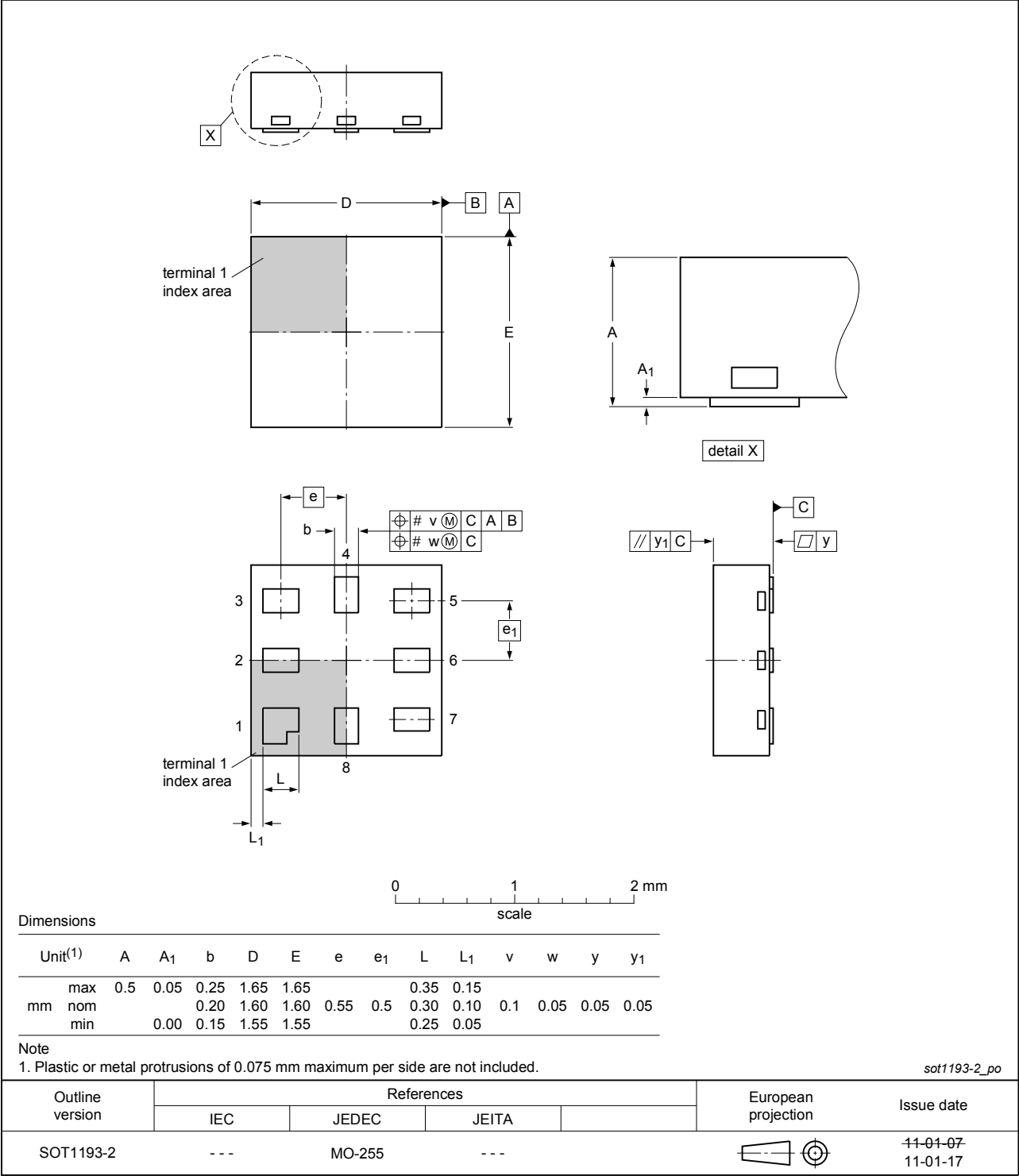


Fig. 1. Package outline XQFN8 (SOT1193-2)

3. Legal information

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